EESTI STANDARD

EVS-EN 60539-1:2016

Directly heated negative temperature coefficient thermistors - Part 1: Generic specification

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See Eesti standard EVS-EN 60539-1:2016 sisaldab Euroopa standardi EN 60539-1:2016 ingliskeelset teksti.	This Estonian standard EVS-EN 60539-1:2016 consists of the English text of the European standard EN 60539-1:2016.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
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ICS 31.040.30

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 60539-1

July 2016

ICS 31.040.30

Supersedes EN 60539-1:2008

English Version

Directly heated negative temperature coefficient thermistors - Part 1: Generic specification (IEC 60539-1:2016)

Thermistances à coefficient de température négatif à chauffage direct - Partie 1: Spécification générique
(IEC 60539-1:2016)

Direkt geheizte temperaturabhängige Widerstände mit negativem Temperaturkoeffizienten -
Teil 1: Fachgrundspezifikation
(IEC 60539-1:2016)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Ref. No. EN 60539-1:2016 E

European foreword

The text of document 40/2430/FDIS, future edition 3 of IEC 60539-1, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60539-1:2016.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2017-03-01
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2019-06-01

This document supersedes EN 60539-1:2008.

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60027-1	NOTE	Harmonized as EN 60027-1.
ISO 80000-1:2009	NOTE	Harmonized as EN ISO 80000-1:2013 (not modified).

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

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The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60062	-	Marking codes for resistors and capacitors	EN 60062	-
IEC 60068-1	2013	Environmental testing - Part 1: General and guidance	EN 60068-1	2014
IEC 60068-2-1	-	Environmental testing - Part 2-1: Tests - Test A: Cold	EN 60068-2-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	-
IEC 60068-2-6	-	Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)	EN 60068-2-6	-
IEC 60068-2-11	-	Basic environmental testing procedures - Part 2-11: Tests - Test Ka: Salt mist	EN 60068-2-11	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-17	-	Basic environmental testing procedures - Part 2-17: Tests - Test Q: Sealing	EN 60068-2-17	-
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	-
IEC 60068-2-21	-	Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	-
IEC 60068-2-27	-	Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock	EN 60068-2-27	-

Publication	Year	Title	EN/HD	Year
IEC 60068-2-31	-	Environmental testing - Part 2-31: Tests - Test Ec: Rough handling shocks, primarily for equipment-type specimens	EN 60068-2-31	-
IEC 60068-2-38	-	Environmental testing - Part 2-38: Tests - Test Z/AD: Composite temperature/humidity cyclic test	EN 60068-2-38	-
IEC 60068-2-45	1980	Basic environmental testing procedures - Part 2-45: Tests - Test XA and guidance: Immersion in cleaning solvents	EN 60068-2-45	1992
+ A1	1993		+ A1	1993
IEC 60068-2-52	-	Environmental testing - Part 2-52: Tests - Test Kb: Salt mist, cyclic (sodium chloride solution)	EN 60068-2-52	-
IEC 60068-2-54	-	Environmental testing - Part 2-54: Tests - Test Ta: Solderability testing of electronic components by the wetting balance method	EN 60068-2-54	-
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-69	-	Environmental testing - Part 2: Tests - Test Te: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method	EN 60068-2-69	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60294	-	Measurement of the dimensions of a cylindrical component with axial terminations	EN 60294	-
IEC 60717	-	Method for the determination of the space required by capacitors and resistors with unidirectional terminations	EN 60717	-
IEC 61193-2	-	Quality assessment systems - Part 2: Selection and use of sampling plans for inspection of electronic components and packages	EN 61193-2	-
IEC 61249-2-7	-	Materials for printed boards and other interconnecting structures - Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7	-

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